

1. Do not give this product a strong press-force nor a mechanical shock. Because such mechanical forces may cause cracking or chipping of this ceramic product.
2. Rapid cooling or heating during soldering is not recommended.
Such treatment may destroy the element.
3. When this product is operated, temperature of some area may be over 100 to 150°C. Be sure that surrounding parts and inserting material can withstand the temperature. If the surrounding part and material is kept under such condition, they may be deteriorated or may produce harmful gases (Cl₂, H₂S, NH₃, SO_x, NO_x etc.). And, such harmful gas may deteriorate the element.
4. Do not assemble this product with air-sealing or resin casting. Such sealing may deteriorate the characteristic or destroy PTC element.
5. Location on Printed Circuit Board (PC Board)

